

-	51	((remote adj plasma) and ('WF.sub.6' and 'SiH.sub.4')) and ((showerhead or dispenser or diffuser) same (temperature or heat\$3 or cool\$3))) and clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 14:50
-	266	134/1.cccls. and (clean\$3 and (chamber or apparatus)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 14:51
-	998	134/1.cccls. and method.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 14:52
-	165	(134/1.cccls. and (clean\$3 and (chamber or apparatus)).ti.) and method.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 14:52
-	76	((134/1.cccls. and (clean\$3 and (chamber or apparatus)).ti.) and method.ti.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:12
-	488	134/1.1.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:12
-	78	134/1.1.cccls. and (remote adj plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:13
-	33	134/1.1.cccls. and ((shower adj head) or diffuser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:17
-	1	134/1.cccls. and (heat\$3 near showerhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:21
-	3	134/1.1.cccls. and heat\$3 near showerhead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:21
-	3	134/1.1.cccls. and (heat\$3 near showerhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:31
-	17	134/1.1.cccls. and (heat\$3 near (showerhead or diffuser or distribut\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/23 15:32
-	1541008	wafer or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 08:09
-	0	(wafer or semiconductor) and (((shower adj head) or diffuser) near (cool\$3 near solution))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 08:11

	13	((wafer or semiconductor) and (((shower adj head) or diffuser) near cool\$3)) and clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 08:12
	33	(wafer or semiconductor) and (((shower adj head) or diffuser) near cool\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 08:14
	345	134/1.2.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 08:58
	23	134/1.2.cccls. and showerhead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 09:27
	197	216/69.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 09:30
	10	216/69.cccls. and (showerhead or diffuser or (diffusion near plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:22
	0	118/723.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:22
	1341	118/723e.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:23
	68415	showerhead or (shower adj head) or diffuser or (diffusion adj plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:24
	239	118/723e.cccls. and (showerhead or (shower adj head) or diffuser or (diffusion adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:24
	21	(118/723e.cccls. and (showerhead or (shower adj head) or diffuser or (diffusion adj plate))) and ((shower adj head) or diffuser or (diffusion adj plate)) same cool\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 11:01
	8422	(showerhead or (shower adj head) or diffuser or (diffusion adj plate)) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 11:02
	91	((showerhead or (shower adj head) or diffuser or (diffusion adj plate)) and (wafer or semiconductor)) and ((shower adj head) or diffuser or (diffusion adj plate)) near (temperature or '.deg.C')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 11:04
	91	((showerhead or (shower adj head) or diffuser or (diffusion adj plate)) and (wafer or semiconductor)) and ((shower adj head) or diffuser or (diffusion adj plate)) near (temperature or '.degree.C')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 11:13

